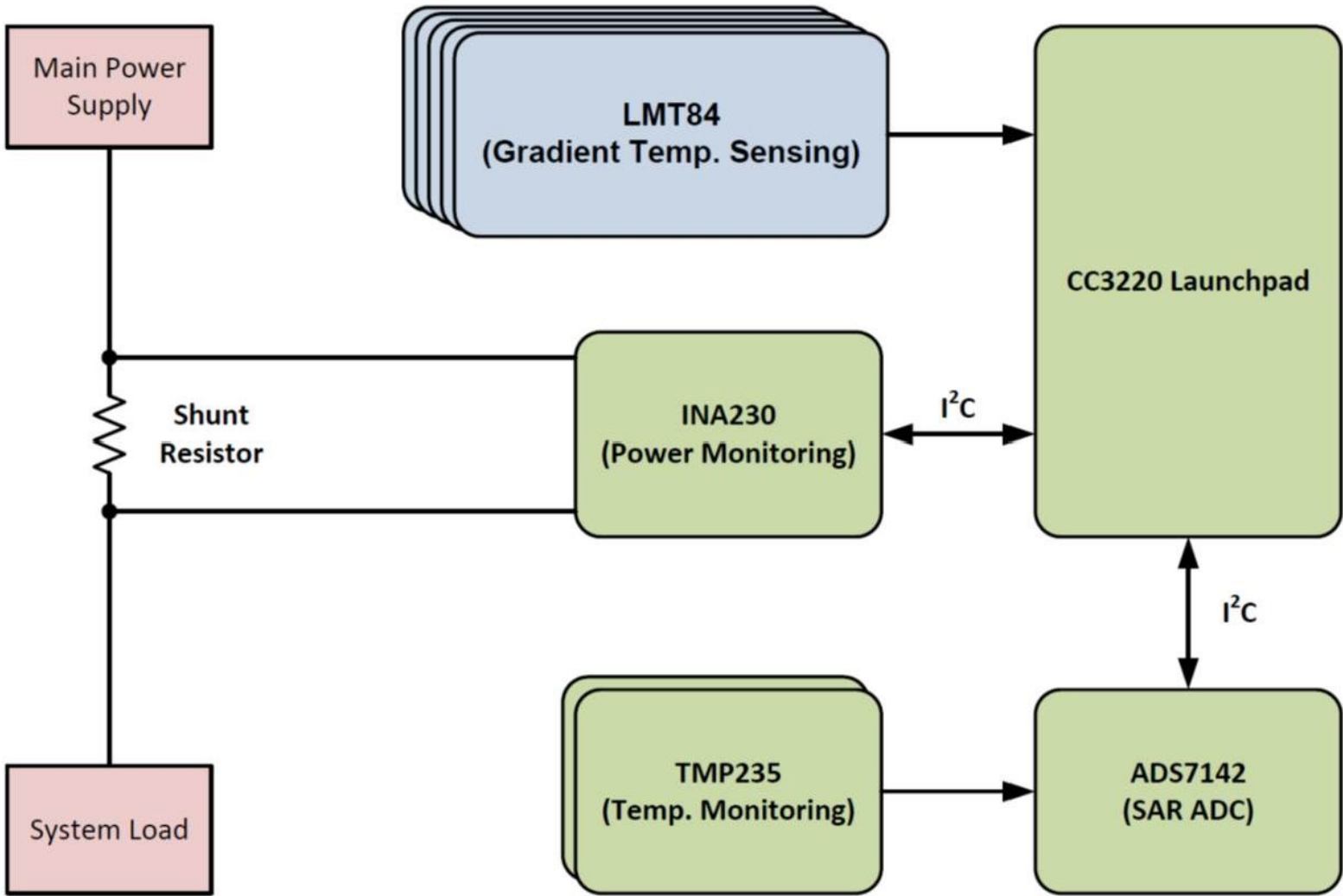


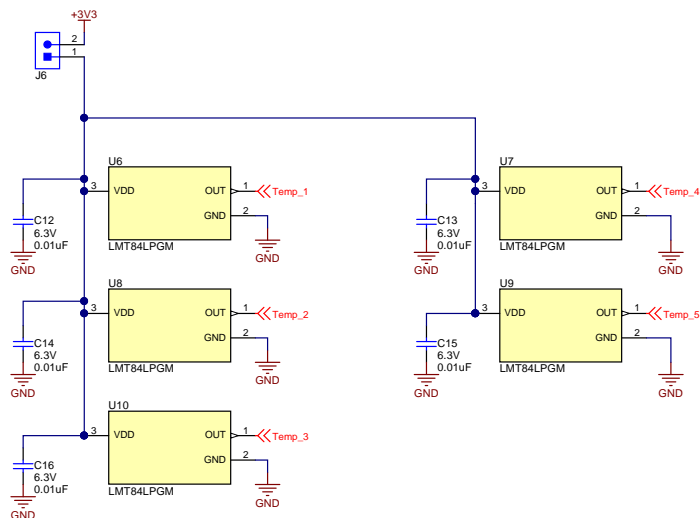
Revision History				
Rev	ECN #	Approved Date	Approved by	Notes
N/A	N/A	N/A	N/A	N/A



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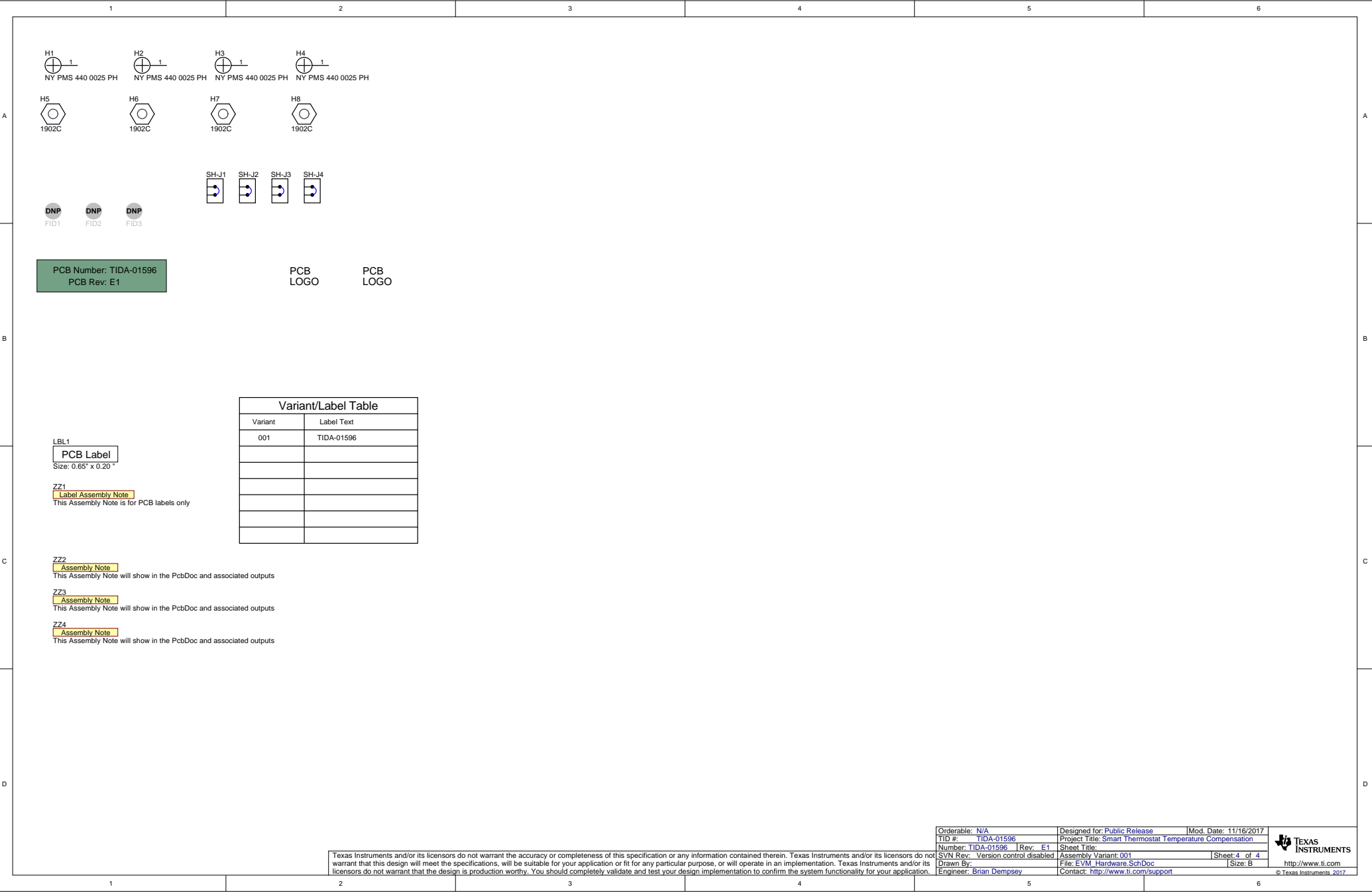
Orderable: N/A	Designed for: Public Release	Mod. Date: 11/16/2017
TID #: TIDA-01596	Project Title: Smart Thermostat Temperature Compensation	
Number: TIDA-01596 Rev: E1	Sheet Title:	
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 1 of 4
Drawn By:	File: CoverSheet.SchDoc	Size: B
Engineer: Brian Dempsey	Contact: http://www.ti.com/support	

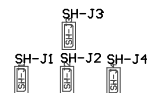




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Orderable: N/A	Designed for: Public Release	Mod. Date: 11/16/2017
TID #: TIDA-01596	Project Title: Smart Thermostat Temperature Compensation	
Number: TIDA-01596 Rev: E1	Sheet Title:	
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 3 of 4
Drawn By:	File: Gradient Board Temp Sensors SchDoc	Size: B
Engineer: Brian Dempsey	Contact: http://www.ti.com/support	





DESIGN INFORMATION

MIN. TRACK WIDTH: 8 MIL
MIN. CLEARANCE: 0.2 mm
MIN. VIA PAD SIZE: 24 MIL
MINIMUM ANNUAL RING 0.05mm (2MIL) EXTERNAL
PER IPC-D-275 CLASS 2 LEVEL C
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL
HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED): +/- 3 MIL

MATERIAL:

☐ FR-408 ☒ FR-4 High Tg ☐ OTHER _____
THICKNESS: ☒ 31 MIL (0.8mm) +/-10% ☐ OTHER _____
TOLERANCE: ☒ ANSI IPC-6012 TYPE 3 CLASS 2
☐ OTHER +/- _____
BOW & TWIST: ☒ ANSI IPC-6012 TYPE 3 CLASS 2
☐ OTHER +/- _____

DRILLING:

REFERENCE: ☒ AS SHOWN ☒ NC DRILL FILES
PTH COPPER THICKNESS: ☒ 20-30 μ m ☐ OTHER _____

BOARD FINISH:

SILKSCREEN: ☒ TOP ☒ BOTTOM
SILKSCREEN COLOR: ☒ WHITE ☐ OTHER _____
SOLDER RESIST COLOR: ☐ GREEN ☒ OTHER Red
☐ MATTE ☐ SEMI-GLOSS

SURFACE FINISH: ☒ IMMERSION GOLD (ENG) ☐ ENPEG
☐ MM. TIN/SILVER OR EQUIV ☐ OTHER _____

ARRAY/PANEL: ☒ CUT AND TRIM PER M1 BOARD OUTLINE
☐ N.C. ROUTE ☐ V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBs
TO MEET OR EXCEED THE REQUIREMENTS OF:
☒ ANSI IPC-A-600F CLASS -> ☐ 1 ☒ 2 ☐ 3
☐ RoHS ☐ OTHER PER ORDER _____

ALL BOARDS MUST MEET OR EXCEED UL94-V0 REQUIREMENTS.
PCB MUST BEAR THE UL94V-0 UL EXCEEDING MATERIAL D NUMBER

ADDITIONAL REQUIREMENTS:

MICROSECTION: ☐ YES ☐ NO
BASE BOARD ELEC. TEST: ☐ NONE ☒ REQUIRED ☐ PER ORDER
☒ XX MIL VIAS REQUIRE NON-CONDUCTIVE FILL AND PLANARIZE
☒ XX MIL VIAS REQUIRE CONDUCTIVE FILL AND PLANARIZE
☐ OUTER XX MIL VAS REQUIRE 50 OHM SINGLE-ENDED IMPEDANCE
☐ LAYER 2 & 3 (INNER LAYERS) XX MIL WIDE, XX MIL SPACE
☐ TRACES REQUIRE 100 OHM DIFFERENTIAL IMPEDANCE



ENGINEER:	LAYOUT BY:
Brian Dempsey	Brian Dempsey
SCALE: 1.00	ALTIM DESIGNER VERSION:
	17.1.5.472

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